

FIG. 1

1	n-TYPE GAN EMITTER LAYER (Si:5x10 <sup>19</sup> cm <sup>-3</sup> ,40nm)
2	p-TYPE InGAN BASE LAYER (ln:7%,Mg:1x10 <sup>19</sup> cm <sup>-3</sup> ,100nm)
3	GRADED InGaN LAYER(30nm)
45	n-TYPE GAN COLLECTOR LAYER (Si:1x10 <sup>17</sup> cm <sup>-3</sup> ,500nm)
5~	n-TYPE GaN SUB-COLLECTOR LAYER $(1\mu m)$
65	Aln buffer LAYER(100nm)
75	SiC SUBSTRATE

FIG. 2

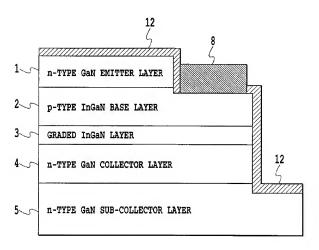


FIG. 3

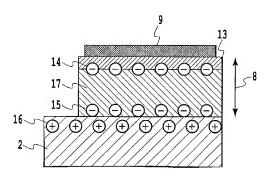


FIG. 4

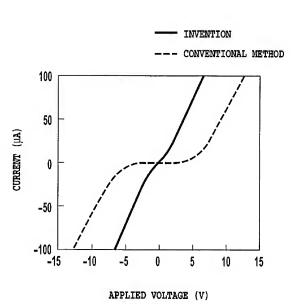
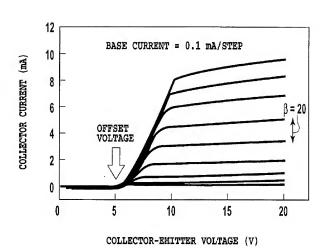


FIG. 5



PRIOR ART FIG. 6

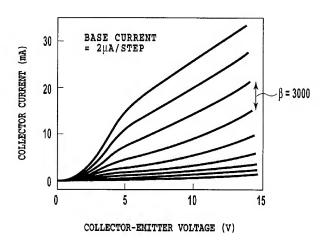


FIG. 7

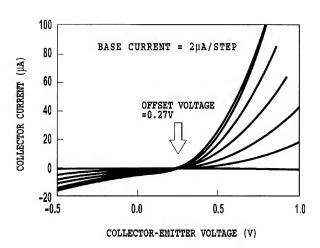


FIG. 8

## 9/10



FIG.9B PRIOR ART

CRYSTAL GROWTH HBT STRUCTURE

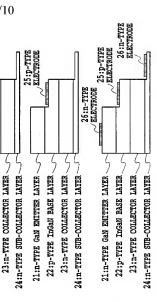
SURFACE EXPOSURE OF BASE LAYER BY ETCHING

FIG.9C PRIOR ART SURFACE EXPOSURE OF SUB-COLLECTOR LAYER BY ETCHING

22:p-TYPE InGaN BASE LAYER

PRIOR ART FORMATION OF p-TYPE ELECTRODE ON BASE LAYER FIG.9D

FIG.9E PRIOR ART FORMATION OF n-TYPE ELECTRODES ON EMITTER LAYER AND SUB-COLLECTOR LAYER



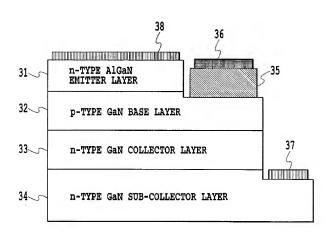


FIG. 10